### Purpose:
The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

### 1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

<table>
<thead>
<tr>
<th>Item Description</th>
<th>Notes</th>
<th>Quantity of items included in product</th>
</tr>
</thead>
<tbody>
<tr>
<td>Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)</td>
<td>With a surface greater than 10 sq cm</td>
<td>4</td>
</tr>
<tr>
<td>Batteries</td>
<td>All types including standard alkaline and lithium coin or button style batteries</td>
<td>2</td>
</tr>
<tr>
<td>Mercury-containing components</td>
<td>For example, mercury in lamps, display backlights, scanner lamps, switches, batteries</td>
<td>0</td>
</tr>
<tr>
<td>Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm</td>
<td>Includes background illuminated displays with gas discharge lamps</td>
<td>1</td>
</tr>
<tr>
<td>Cathode Ray Tubes (CRT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Capacitors / condensers (Containing PCB/PCT)</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>External electrical cables and cords</td>
<td></td>
<td>1</td>
</tr>
<tr>
<td>Gas Discharge Lamps</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Plastics containing Brominated Flame Retardants</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner</td>
<td>Include the cartridges, print heads, tubes, vent chambers, and service stations.</td>
<td>0</td>
</tr>
<tr>
<td>Components and waste containing asbestos</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Components, parts and materials containing refractory ceramic fibers</td>
<td></td>
<td>0</td>
</tr>
<tr>
<td>Components, parts and materials containing radioactive substances</td>
<td></td>
<td>0</td>
</tr>
</tbody>
</table>
2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

<table>
<thead>
<tr>
<th>Tool Description</th>
<th>Tool Size (if applicable)</th>
</tr>
</thead>
<tbody>
<tr>
<td>Description #1</td>
<td>Screwdriver Type-cross #1 (JIS B 4633-1987)</td>
</tr>
<tr>
<td>Description #2</td>
<td></td>
</tr>
<tr>
<td>Description #3</td>
<td></td>
</tr>
<tr>
<td>Description #4</td>
<td></td>
</tr>
<tr>
<td>Description #5</td>
<td></td>
</tr>
</tbody>
</table>

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Get out cell battery.
2. Loose four M2.5*5.5L screws on rear HDD door and losse two M2.5*6.5 screws on HDD bracket then take out the HDD & RAM.
3. Loose a M2.5*5.5L screw on rear Wireless door and loose a M2.0*3 screw on mini card then take out the antenna connector and mini card.
4. Loose a M2.5*6.5L screw on BASE cover then take out the ODD.
5. Loose five M2.5*6.5L screws on BASE cover rear side then take out the Keyboard.
6. Loose six M2.5*6.5L screws with triangle mark and five M2.5*3L screws with triangle mark which is locate on battery cavity on BASE rear side; loose one M2.5*6.5L screws on front side then take out the KB retainer.
7. Loose seven M2.5*6.5L screws on Base side and loose one M2.5*6.5L screws on front side then take out the FFC cable of T/P module to take out the kb deck.
8. Take out the LCD & CCD & MIC connector on MB & Loose four M2.5*6.5L screws on hinge support of R/L side to take out the LCD module.
9. Take out the speaker connector on MB then take out the speaker box.
10. Loose a M2.5*3L screw then take out the power board from KB retainer.
11. Loose a M2.5*6.5L screws of the right hand corner and take out the DC cable and USB FFC cable then take out the MB from BASE case assy.
12. Loose a M2.5*6.5L screws then take out the USB board.
13. Loose a M2.5*6.5L screws then take out the Audio board.
14. Loose five spring screws for DIS; three spring screws for UMA then take out the thermal module from MB.
15. Loose two M2.5*6.5L screws then take out the LCD cover.
16. Loose six M2.5 *5L screws then take out the hinge R/L side.
17. Loose four M2.0 *3L screws then take out the LCD bracket R/L side.
18.
19.
20.
21.
22.
23.
24.

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).
Take out inverter board, then take out LCD module.
Disassembly SOP

[How to disassemble LTN184HT03-001]

Date: June 18, 2008
Customer: HP/Quanta

Prepared by Jay Kim
Assistant Engineer, Application Engineering Group

Checked by KH Shin
Sr. Manager, Application Engineering Group

Jay Kim

Application Engineering Group,
Mobile LCD Division,
Samsung Electronics
1. Purpose
   - To inform HP/Quanta how to disassemble panel

2. General Information
   - Project Name: Morpheus
   - Model: LTN184HT03-001

3. How to disassemble panel
   - Next page
Step 1) Remove yellow tapes and Al tape

- Side yellow tape
- Lamp-wire tape
- Bottom Al tape

Step 2) Remove PCB cover

*Handle with care not to damage COF of S/D and G/D Ic.*
Step 3) Separate Top Chassis from Mold frame

The order: Bottom hook → Side hook [Left & Right]

* Handle with care not to damage COF of S/D and G/D Ic.

Step 4) Separate Panel assembly from BLU